

IMPACT

TE Internal #: 2007716-1

120 Position High Speed Backplane Connector, 12 Row, 10 Column, PCB Mount Receptacle, Right Angle, Unshrouded, 1.9 mm

[.075 in] Centerline, IMPACT

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Connectors > PCB Connectors > Backplane Connectors > High Speed Backplane Connectors











Number of Positions: 120

Row-to-Row Spacing: 1.35 mm [.053 in]

Mating Alignment: With

Mating Alignment Type: Keyed

Number of Rows: 12

Features

Product Type Features

Signal Arrangement	Differential
Connector & Contact Terminates To	Printed Circuit Board
Connector System	Board-to-Board
PCB Connector Type	PCB Mount Receptacle
Shroud Style	Unshrouded
Configuration Features	
Number of Pairs	40
Number of Ground Positions	40
Number of Signal Positions	80
Stackable	No
Number of Positions	120
Number of Rows	12
Number of Columns	10
PCB Mount Orientation	Right Angle



Operating Voltage Impedance Impedanc		
Impedance 100 C Impedance 100	Guide Location	Right
Impedance 1000 O O O O O O O O O O O O O O O O O	Electrical Characteristics	
Data Rate 20 – 25 Gb/s Number of Differential Pairs per Column 4 Sody Features Primary Product Color Black Contact Underplating Material Nickel Contact Underplating Material Thickness 127 µm(50 µin) Contact Underplating Material Thickness 127 µm(50 µin) Contact Harmination Area Plating Material Thickness 127 µm(50 µin) Contact Shape & Form 10 µin 10	Operating Voltage	30 VDC
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	Mating Alignment Type	Keyed



Connector Mounting Type	Board Mount
Housing Features	
Number of Shrouded Sides	0
Housing Material	LCP GF
Centerline (Pitch)	1.9 mm[.075 in]
Dimensions	
PCB Thickness (Recommended)	1 mm
Connector Width	28.2 mm[1.11 in]
PCB Hole Diameter	.39 mm[.015 in]
Connector Height	17.3 mm[.681 in]
Connector Length	26.6 mm[1.047 in]
Row-to-Row Spacing	1.35 mm[.053 in]
Usage Conditions	
Operating Temperature Range	-55 – 85 °C[-67 – 185 °F]
Operation/Application	
Circuit Application	Signal
Industry Standards	
UL Flammability Rating	UL 94V-0
Compatible With Approved Standards Products	UL E28476
Packaging Features	
Packaging Method	Box & Tube, Tube

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2025 (247) Candidate List Declared Against: JAN 2025 (247) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC



Free

Solder Process Capability

Not applicable for solder process capability

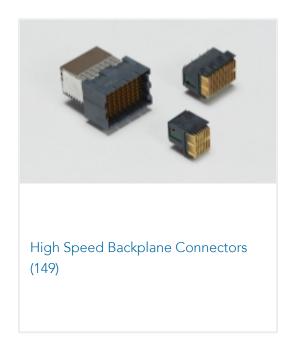
Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts



Also in the Series | IMPACT



Customers Also Bought

















TE Part #2007741-1 IMP100S,R,RA6P10C,UG,39









Documents

CAD Files

Customer View Model

ENG_CVM_CVM_2007716-1_A.2d_dxf.zip

English

3D PDF

3D

Customer View Model

ENG_CVM_CVM_2007716-1_A.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_2007716-1_A.3d_stp.zip

English

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Datasheets & Catalog Pages

7-1773458-1_IMPACT_BACKPLANE_CONNECTOR_SYSTEM_CATALOG

English

Product Specifications

Application Specification

English

Agency Approvals

Agency Approval Document

English